- 4-Ω Switch Connection Between Two Ports
- TTL-Compatible Control Input Levels
- Make-Before-Break Feature
- Internal 500- Ω Pulldown Resistors to Ground
- Latch-Up Performance Exceeds 250 mA Per JESD 17
- Package Options Include Plastic Thin Shrink Small-Outline (DGG), Thin Very Small-Outline (DGV), and 300-mil Shrink Small-Outline (DL) Packages

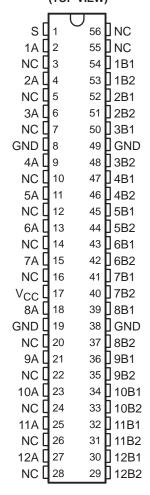
description

The SN74CBT16292 is a 12-bit 1-of-2 high-speed TTL-compatible FET multiplexer/ demultiplexer. The low on-state resistance of the switch allows connections to be made with minimal propagation delay.

When the select (S) input is low, port A is connected to port B1 and R_{INT} is connected to port B2. When S is high, port A is connected to port B2 and R_{INT} is connected to port B1.

The SN74CBT16292 is characterized for operation from –40°C to 85°C.

DGG, DGV, OR DL PACKAGE (TOP VIEW)



NC - No internal connection

FUNCTION TABLE

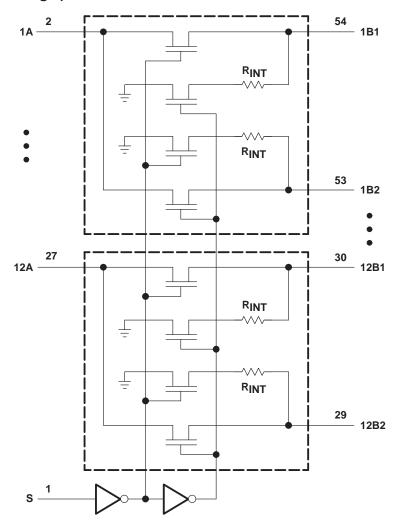
INPUT S	FUNCTION
L	A port = B1 port R _{INT} = B2 port
н	A port = B2 port R _{INT} = B1 port



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logic diagram (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[†]

Supply voltage range, V _{CC}	0.5 V to 7 V
Input voltage range, V _I (see Note 1)	0.5 V to 7 V
Continuous channel current	128 mA
Input clamp current, I _{IK} (V _I < 0)	
Package thermal impedance, θ _{JA} (see Note 2): D0	GG package 81°C/W
DO	GV package 86°C/W
Dl	_ package 74°C/W
Storage temperature range, T _{stq}	

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.

2. The package thermal impedance is calculated in accordance with JESD 51.



recommended operating conditions (see Note 3)

		MIN	MAX	UNIT
VCC	Supply voltage	4	5.5	V
VIH	High-level control input voltage	2		V
V _{IL}	Low-level control input voltage		0.8	V
TA	Operating free-air temperature	-40	85	°C

NOTE 3: All unused control inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PAI	RAMETER	TEST CONDITIONS		MIN	TYP [†]	MAX	UNIT	
VIK		$V_{CC} = 4.5 \text{ V},$	$I_{I} = -18 \text{ mA}$				-1.2	V
Ц		V _{CC} = 5.5 V,	$V_I = V_{CC}$ or GND				±5	μΑ
Icc		V _{CC} = 5.5 V,	$I_{O} = 0,$	$V_I = V_{CC}$ or GND			3	μΑ
∆lcc [‡]	Control input	V _{CC} = 5.5 V,	One input at 3.4 V,	Other inputs at V _{CC} or GND			2.5	mA
C _i	Control input	$V_I = 3 V \text{ or } 0$				3		pF
C _{io}		$V_{CC} = 0$,	$V_O = 3 V \text{ or } 0$			8		pF
r _{on} §		$V_{CC} = 4 \text{ V},$ TYP at $V_{CC} = 4 \text{ V}$	V _I = 2.4 V,	I _I = 15 mA		10	20	
			V _I = 0	I _I = 64 mA		3	7	Ω
		V _{CC} = 4.5 V		I _I = 30 mA		3	7	
			V _I = 2.4 V,	I _I = 15 mA		5	15	

 $[\]dot{T}$ All typical values are at \dot{V}_{CC} = 5 V (unless otherwise noted), T_A = 25°C.

switching characteristics over recommended operating free-air temperature range, $C_L = 50 \text{ pF}$ (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V _{CC} = 4 V	V _{CC} = 5 V ± 0.5 V		UNIT
	(INTOT)	(0011 01)	MIN MAX	MIN	MAX	
$t_{pd}\P$	A or B	B or A	0.5		0.25	ns
t _{en}	S	A or B	6.8	1	6	ns
^t dis	S	A or B	7	1	6.3	ns

The propagation delay is the calculated RC time constant of the typical on-state resistance of the switch and the specified load capacitance, when driven by an ideal voltage source (zero output impedance).

switching characteristics over recommended operating free-air temperature range, C_L = 50 pF (unless otherwise noted) (see Figure 1)

PARAMETER	DESCRIPTION		V _{CC} = 4 V		V _{CC} = 5 V ± 0.5 V	
			MAX	MIN	MAX	
t _{mbb} #	Make-before-break time	0	2	0	2	ns

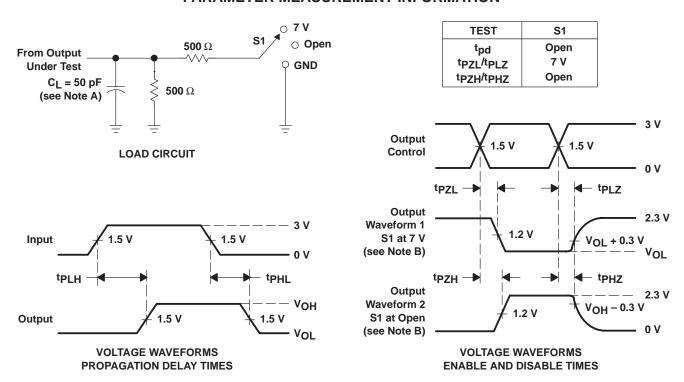
[#]The make-before-break time is the time interval between make and break, during the transition from one selected port to the other.



[‡] This is the increase in supply current for each input that is at the specified TTL voltage level rather than V_{CC} or GND.

[§] Measured by the voltage drop between the A and B terminals at the indicated current through the switch. On-state resistance is determined by the lower of the voltages of the two (A or B) terminals.

PARAMETER MEASUREMENT INFORMATION



NOTES: A. C_L includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when connected to the internal 500-Ω pulldown resistor. Waveform 2 is for an output with internal conditions such that the output is high except when connected to the internal 500-Ω pulldown resistor.
- C. All pulse inputs and DC inputs are supplied by generators having the following characteristics: PRR \leq 10 MHz, $Z_O = 50 \Omega$, $t_f \leq 2.5 \text{ ns}$, $t_f \leq 2.5 \text{ ns}$.
- D. The outputs are measured one at a time with one transition per measurement.
- E. t_{PLZ} and t_{PHZ} are the same as t_{dis} . Z = R_{INT} = 500 Ω
- F. tpzL and tpzH are the same as t_{en} . Z = R_{INT} = 500 Ω
- G. tpLH and tpHL are the same as tpd.

Figure 1. Load Circuit and Voltage Waveforms



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